

# Call for Abstracts (due December 20, 2017)



## ASME 2018 INTERPACK<sup>®</sup>

**International Technical Conference and Exhibition on  
Packaging and Integration of Electronic and Photonic  
Microsystems**

**August 28-30, 2018 at Hilton San Francisco, Financial District, California, USA**

<http://www.asme.org/events/interpack>

InterPACK is the premier international conference for exchange of state-of-the-art knowledge in research, development, manufacturing, and applications of electronics packaging and heterogeneous integration. It is the flagship conference of the ASME Electronic and Photonic Packaging Division (EPPD). The international nature of the meeting has been highly beneficial in promoting global interactions between Industry and Academia. In addition to paper presentations and exhibits, InterPACK 2018 will include panel discussions, workshops, tutorials, keynote and technology talks by prominent speakers, and a Joint Industry, National Lab, Academia poster session. **Abstracts (<400 words) for original papers are solicited in the general track areas of (but not limited to):**

### Heterogeneous Integration:

Advanced Packaging, Die Stacking, Multichip Modules, Interconnect Technology, Substrate Technology, Through-Silicon Vias (TSV), Wafer Level Packaging (Fan-in, Fan-out), Panel Level Packaging, System in Package (SiP), Microsystems Integration, Integrated Photonics, RF Packaging, Advanced Materials and Processes, Chip Package Interaction, Modeling, Characterization and Reliability for Integrated Devices, Electronic Materials, Underfills, Molding Compounds, Substrates, Thermal Materials, Dielectrics.

### Servers of the Future, IoT, and Edge to Cloud:

Data Centers & Energy Efficient Electronic Systems, Cloud Computing Hardware, Internet of Things, Edge to Cloud Systems, Rack Level Cooling, Thermal Interface Materials & Thermal Underfills, Fans & Pumps, Thermosyphons & Refrigeration, Exaflop Computing Systems, Memory, Connectors, Advanced Substrates, Novel Cooling Techniques, Heat Exchangers, Device to System Level Packaging, Nanoscale Heat Transport.

### Structural and Physical Health Monitoring:

Wearables, Asset Monitoring, Implantable Medical Devices, Microfluidics, Interconnects, Substrate Materials, Printed Electronics, Thin Die Handling, Non-Contact Processes. Sensors & Actuators, RF Resonators, Fabrication, Integration, Hermetic Packaging, & Reliability, Biosystems & Biomedicine, and Industry Perspectives. Reliability of devices, Interconnects, Solder Joint Reliability, Materials Interactions, Chemical, Biological, and Physical Implications, System Level Reliability Issues, Materials characterization, Reliability Modelling and Simulation, Reliability Test Methods, Prognostics and Health Monitoring.

### Power Electronics, Energy Conversion, and Storage:

Wide Bandgap Semiconductor Packaging, Power Electronics, Energy Harvesting, Energy Storage, Nanoscale Heat Transport, 2D Materials, Graphene & CNT Materials and Devices, Novel Interconnects, Harsh Environment Sensors, Thermoelectrics, Photovoltaics, High Temperature Electronics for Oil & Gas and Geothermal Energy. Fracture, Fatigue, and Delamination of Interfaces and Interconnects, Thermomechanical Stress and Device Reliability.

### Autonomous, Hybrid, and Electric Vehicles:

Electronics for Vehicle Electrification, High Temperature Sensors, RADAR, LIDAR, Advanced Driver Assistance System (ADAS) Electronics, MEMS packaging, Control Systems, Electronic Materials, Nanosatellites, Unmanned Aerial Vehicle (UAV) Electronics, Hybrid Packaging, Prognostic Health Monitoring, Vehicle Charging, Wireless Power Transfer, Energy Conversion, Electric Drive Technologies e.g. Electric Machines, Motor Control Sensing, and Battery Management.

#### Publication Schedule:

Abstract Submission:	<del>December 1, 2017</del> <b>December 20, 2017</b>
Draft Paper Submission:	February 16, 2018
Draft Paper Acceptance Notification:	March 30, 2018
Submission of Revised Draft Papers:	April 20, 2018
Submission of Copyright:	May 11, 2018



#### Direct general inquiries to:

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